

ABSTRACT

A circuit board and a fabricating process thereof is provided. The present invention employs a core layer as a base layer, wherein the core layer is a core conducting layer, or is a core dielectric layer having two conducting layers. By using
5 this core layer and two patterned conductive layers, a three-conducting-layer circuit board or a four-conducting-layer circuit board is fabricated. Furthermore, both circuit boards can be used as circuit board units to fabricate circuit boards having more than four conducting layers. The present invention adopts lamination processes and equipment instead of using complicated build-up process. Therefore, the present
10 invention effectively reduces the production costs and simplifies the process cycle for fabricating circuit boards, and is suitable for mass production.